

IN THE CLAIMS:

Claims 1-14 and 43-50 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

Listing of Claims:

1.-14. (Cancelled)

15. (Previously presented) A method for forming a mold gate of a tape substrate, comprising:  
forming an aperture of the mold gate in a flexible dielectric film of the tape substrate; and  
concurrently patterning conductive lines and a support structure of the mold gate from the same conductive film, the support structure at least partially overlapping the aperture.

16. (Previously presented) The method of claim 15, further comprising:  
securing the conductive film to the flexible dielectric film.

17. (Previously presented) The method of claim 16, wherein securing the conductive film is effected before forming an aperture of the mold gate.

18. (Previously presented) The method of claim 17, wherein forming an aperture comprises etching the flexible dielectric film.

19. (Previously presented) The method of claim 18, wherein etching the flexible dielectric film comprises at least one of wet etching and dry etching the flexible dielectric film.

20. (Previously presented) The method of claim 16, wherein securing the conductive film is effected following forming an aperture of the mold gate.

21. (Previously presented) The method of claim 20, wherein forming an aperture comprises mechanically removing material of the flexible dielectric film.

22. (Previously presented) The method of claim 21, wherein mechanically removing material comprises die cutting the flexible dielectric film.

23. (Previously presented) The method of claim 15, wherein concurrently patterning comprises:  
forming a mask over the conductive film; and  
removing material of the conductive film through apertures of the mask.

24. (Previously presented) The method of claim 23, wherein removing material comprises etching the conductive film.

25. (Previously presented) The method of claim 15, further comprising:  
coating sidewalls of the aperture with a material that reduces or prevents adhesion of a packaging material to the mold gate.

26. (Previously presented) A method for fabricating a tape substrate, comprising:  
providing a flexible dielectric film;  
forming an aperture of a mold gate in the flexible dielectric film; and  
substantially concurrently forming a support element of the mold gate and conductive traces from a single conductive film laminated onto a surface of the flexible dielectric film, the support structure at least partially overlapping the aperture.

27. (Previously presented) The method of claim 26, wherein providing the flexible dielectric film comprises providing the flexible dielectric film with the single conductive film prelaminated onto the surface thereof.

28. (Previously presented) The method of claim 26, wherein providing the flexible dielectric film comprises providing the flexible dielectric film without the single conductive film on the surface thereof.

29. (Previously presented) The method of claim 28, further comprising:  
laminating the single conductive film onto the surface of the flexible dielectric film.

30. (Previously presented) The method of claim 29, wherein laminating is effected following forming the aperture.

31. (Previously presented) The method of claim 30, wherein forming the aperture comprises mechanically forming the aperture.

32. (Previously presented) The method of claim 31, wherein mechanically forming the aperture comprises die cutting the flexible dielectric film.

33. (Previously presented) The method of claim 26, wherein forming the aperture comprises mechanically forming the aperture.

34. (Previously presented) The method of claim 33, wherein mechanically forming the aperture comprises die cutting the flexible dielectric film.

35. (Previously presented) The method of claim 26, wherein forming the aperture comprises:

forming a mask on a surface of the flexible dielectric film; and  
removing material of the flexible dielectric film through apertures of the mask.

36. (Previously presented) The method of claim 35 wherein removing comprises etching the material of the flexible dielectric film.

37. (Previously presented) The method of claim 36, wherein etching comprises at least one of dry etching and wet etching the material of the flexible dielectric film.

38. (Previously presented) The method of claim 26, wherein forming the aperture is effected at a location which is external to an outer boundary of an area of the flexible dielectric film where a finished tape substrate is to be located.

39. (Previously presented) The method of claim 26, wherein substantially concurrently forming comprises:  
forming a mask over the single conductive film; and  
removing material of the single conductive film through apertures of the mask.

40. (Previously presented) The method of claim 39, wherein removing material comprises etching the single conductive film.

41. (Previously presented) The method of claim 26, further comprising:  
coating sidewalls of the aperture with a material that reduces or prevents adhesion of a packaging material to the mold gate.

42. (Previously presented) The method of claim 26, further comprising plating conductive structures of the support element.

43.-50. (Cancelled)